AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 10/633,940 Filing Date: August 4, 2003

Title: I/C PACKAGE/THERMAL-SOLUTION RETENTION MECHANISM WITH SPRING EFFECT

Assignee: Intel Corporation

## **IN THE SPECIFICATION**

Page 2

Dkt: 884.355US2 (INTEL)

Please amend the specification as follows:

The paragraph beginning at page 1, immediately after the title, is amended as follows:

This application is a continuation of U.S. Patent Application Serial No. 09/733,476, filed

December 8, 2000, now issued as U.S. Patent 6,657,131, which is incorporated herein by reference.